



Material Content Data Sheet



Sales Product Name	TLE4998S3			Issued	24. January 2018			
MA#	MA001678506							
Package	PG-SSO-3-10			Weight*	142.97 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.851	2.69	2.69	26940	26940
leadframe	inorganic material	silicon	7440-21-3	0.020	0.01		138	
	non noble metal	titanium	7440-32-6	0.099	0.07		692	
	non noble metal	chromium	7440-47-3	0.297	0.21		2076	
wire	non noble metal	copper	7440-50-8	98.494	68.90	69.19	688941	691847
	noble metal	gold	7440-57-5	0.047	0.03	0.03	329	329
	encapsulation	organic material	carbon black	1333-86-4	0.357	0.25		2497
encapsulation	plastics	epoxy resin	-	4.511	3.16		31553	
	inorganic material	silicondioxide	60676-86-0	27.585	19.30	22.71	192951	227001
leadfinish	non noble metal	tin	7440-31-5	5.779	4.04	4.04	40426	40426
plating	noble metal	silver	7440-22-4	0.604	0.42	0.42	4222	4222
glue	plastics	epoxy resin	-	0.264	0.18		1847	
	noble metal	silver	7440-22-4	1.056	0.74	0.92	7388	9235
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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